[WeE3] Reliability and Integration Challenges in Advanced Packaging	
Session Date	November 12 (Wed.), 2025
Session Time	16:05-17:35
Session Room	Room E (Sicily Room, 1F)
Session Chair	Prof. Tae-Dong Kim (Hannam Univ., Korea)

[WeE3-1] [Invited] **16:05-16:25**

Emerging CMP Solutions for Next Generation Advanced Packaging Process

Jae-Dong Lee, Eunok Kim, Yeongjung Kim, Hyungoo Kong, Jae Hak Lee, and Seung Mahn Lee (KCTech, Korea)

[WeE3-2] [Invited] **16:25-16:55**

Wet Cleaning Process Issues with Memory Device Scaling

Young-Hoo Kim, Pyojin Jeon, Junho Yun, Junho Lee, Yongwook Lee, Gunshik Yun, Sunghyun Park, Jungwan Han, Ji-Hoon Jeong, Tae-Hong Kim, Woogwan Shim, Sungyong Park, and Hyosan Lee (Samsung Electronics Co., Ltd., Korea)

[WeE3-3] **16:55-17:15**

Fenton Reaction Enhancing Significant Chemical Oxidation for Ag Chemical Mechanical Planarization

Man-Hyup Han, Hyun-Sung Koh, Il-Haeng Heo, Min-Ji Kim, Woo-Hyun Jin, Jin-Woo Kim, Seung-Hwan Kim, Jin-Sub Park, and Jea-Gun Park (Hanyang Univ., Korea)

[WeE3-4] **17:15-17:35**

Si-Wafer Polishing Rate Enhancement by Amine Functional Group as Hydrolysis Reaction Accelerator

Min-Uk Jeon, Pil-Su Kim, Se-Hui Lee, Hye-Min Lee, Su-Bin Kim, Ji-Hye Shin (Hanyang Univ., Korea), Jin-Hyung Park (ENF Technology. Co., Ltd., Korea), Kyoo-Chul Cho (Hanyang Univ., Korea), Tae-Dong Kim (Hannam Univ., Korea), Jin-Sub Park, and Jea-Gun Park (Hanyang Univ., Korea)